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# S21ME8/S21ME8F

## High Repetitive Peak OFF-State Voltage Type Phototriac Couplers

### ■ Features

- High repetitive peak OFF-state voltage ( $V_{DRM}$ : MIN. 800V)
- Low minimum trigger current ( $I_{FT}$ : MAX. 3mA)
- Internal insulation distance : 0.5mm or more
- Long creepage distance type  
(Creepage distance : 8mm or more)
- Built-in zero-cross circuit
- High isolation voltage between input and output  
( $V_{iso}$  : 5 000V<sub>rms</sub>)
- Recognized by UL file No. E64380  
Approved by BSI, No. 6690, No. 7421  
Approved by SEMKO, No. 9843099  
Approved by DEMKO, No. 308207  
\*DIN-VDE 0884 approved type is also available as an option  
**(S21ME8Y/S21ME8FY)**  
Approved by VDE, No. 77294

### ■ Applications

- For triggering medium/high power triac

### ■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	*1 Forward current	$I_F$	15	mA
	Reverse voltage	$V_R$	6	V
Output	*1 RMS ON-state current	$I_T$	0.1	A <sub>rms</sub>
	Peak one cycle surge current	$I_{surge}$	*3 1.2	A
	Repetitive peak OFF-state voltage	$V_{DRM}$	800	V
Operating temperature		$T_{opr}$	-30 to +100	°C
Storage temperature		$T_{stg}$	-55 to +125	°C
*2 Isolation voltage		$V_{iso}$	5 000	V <sub>rms</sub>
Soldering temperature		$T_{SOL}$	*4 260	°C

\*1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1 to 2.

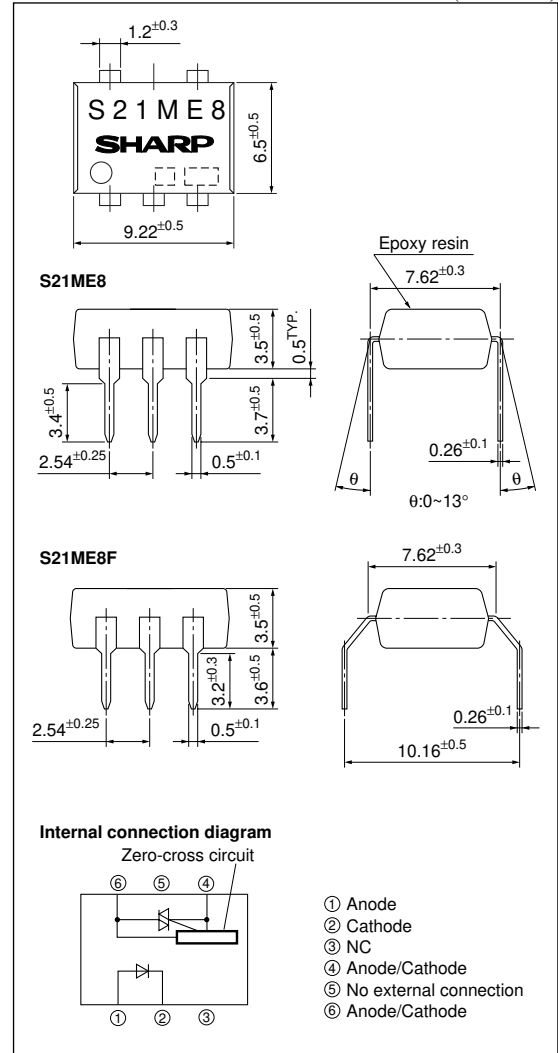
\*2 40 to 60%RH, AC for 1min, f=60Hz.

\*3 50Hz, sine wave.

\*4 For 10s.

### ■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(T<sub>a</sub>=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V <sub>F</sub>	I <sub>F</sub> =6mA	-	1.2	1.4	V
	Reverse current	I <sub>R</sub>	V <sub>R</sub> =3V	-	-	10 <sup>-5</sup>	A
Output	Repetitive peak OFF-state current	I <sub>DRM</sub>	V <sub>DRM</sub> =Rated	-	-	10 <sup>-6</sup>	A
	ON-state voltage	V <sub>T</sub>	I <sub>T</sub> =0.1A	-	1.7	3.0	V
	Holding current	I <sub>H</sub>	V <sub>D</sub> =6V	0.1	-	3.5	mA
	Critical rate of rise of OFF-state voltage	dV/dt	V <sub>DRM</sub> =1/√2-Rated	500	-	-	V/μs
Transfer characteristics	Zero-cross voltage	V <sub>ox</sub>	I <sub>F</sub> =6mA, Resistance load	-	-	20	V
	Minimum trigger current	I <sub>FT</sub>	V <sub>D</sub> =6V, R <sub>L</sub> =100Ω	-	-	3.0	mA
	Isolation resistance	R <sub>iso</sub>	DC=500V, 40 to 60%RH	5×10 <sup>-10</sup>	1×10 <sup>-11</sup>	-	Ω
	Turn-on time	t <sub>on</sub>	V <sub>D</sub> =6V, R <sub>L</sub> =100Ω, I <sub>F</sub> =6mA	-	-	50	μs

Fig.1 RMS ON-state Current vs. Ambient Temperature

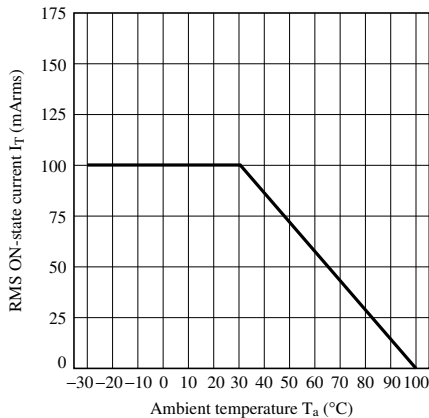


Fig.2 Forward Current vs. Ambient Temperature

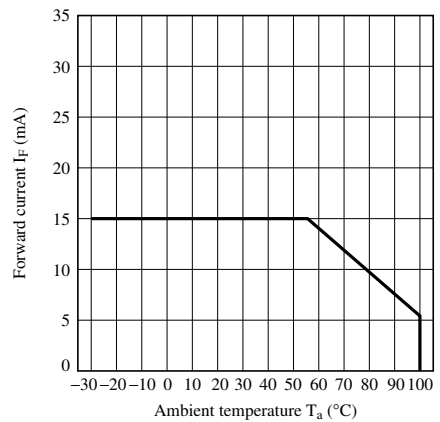


Fig.3 Forward Current vs. Forward Voltage

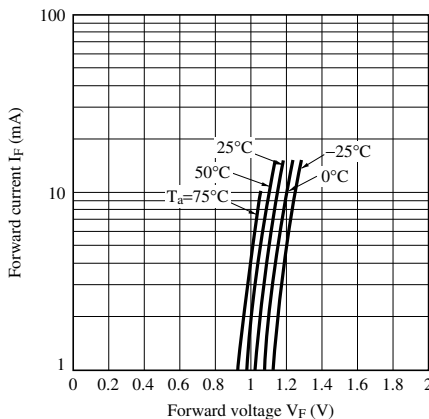
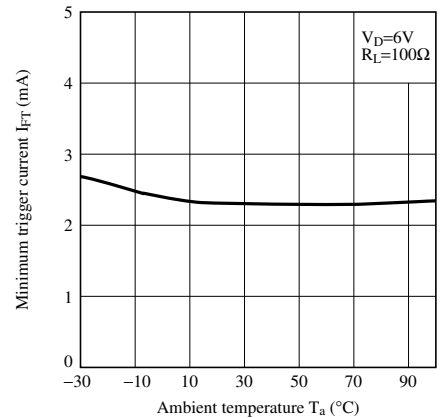
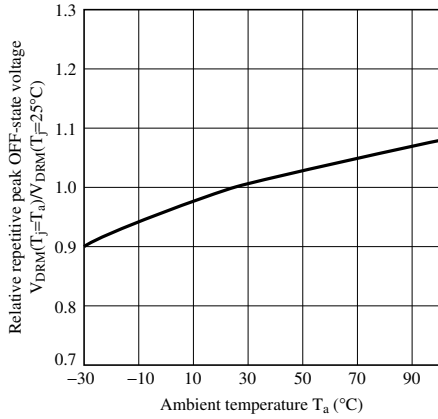


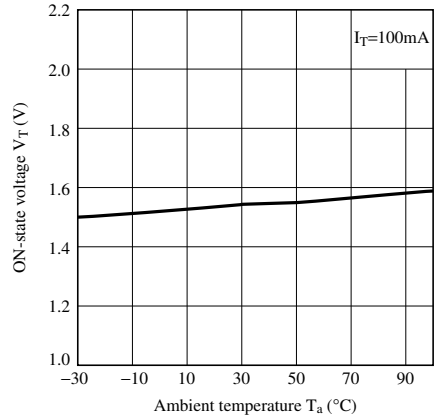
Fig.4 Minimum Trigger Current vs. Ambient Temperature



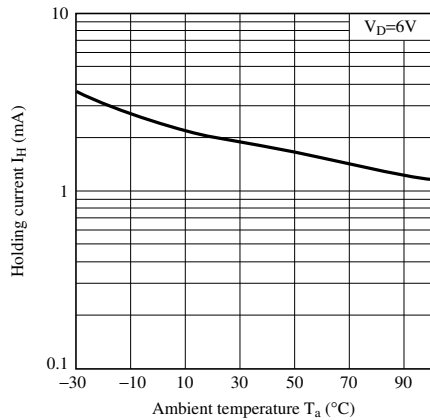
**Fig.5 Relative Repetitive Peak OFF-state Voltage vs. Ambient Temperature**



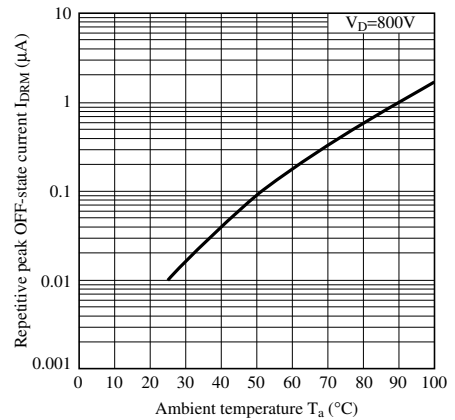
**Fig.6 ON-state Voltage vs. Ambient Temperature**



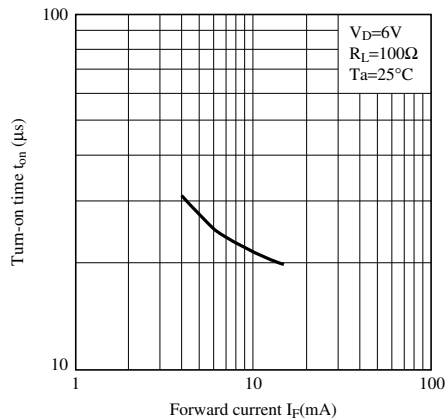
**Fig.7 Holding Current vs. Ambient Temperature**



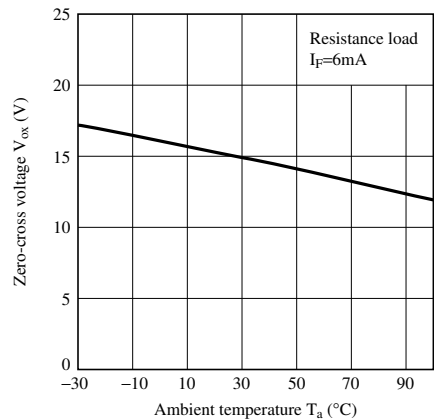
**Fig.8 Repetitive Peak OFF-state Current vs. Ambient Temperature**



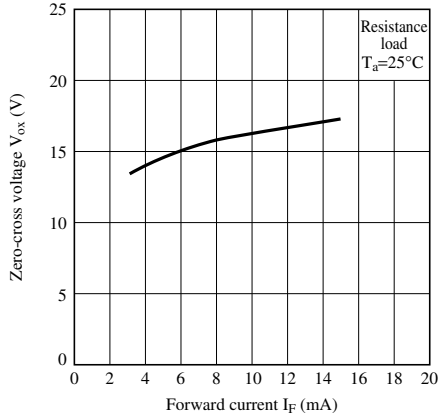
**Fig.9 Turn-on Time vs. Forward Current**



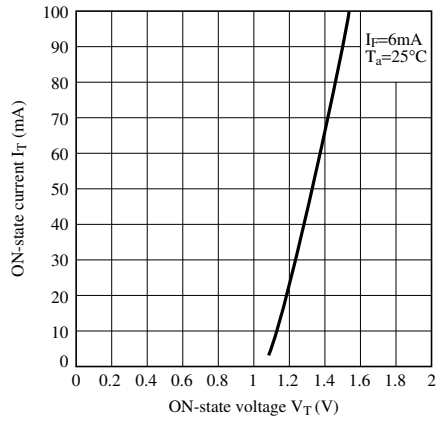
**Fig.10 Zero-cross Voltage vs. Ambient Temperature**



**Fig.11 Zero-cross Voltage vs. Forward Current**

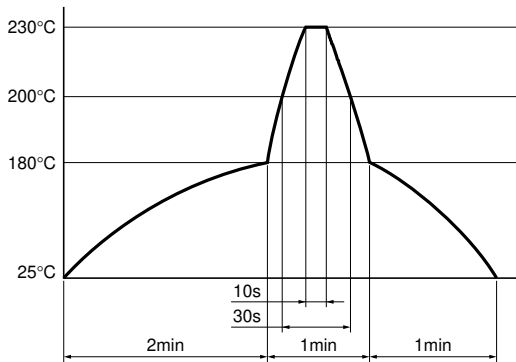


**Fig.12 ON-state Current vs. ON-state Voltage**



**Fig.13 Reflow Soldering**

Only one time soldering is recommended within the temperature profile shown below.



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